IPC ASSOCIATION CON ELECTRONICS IND	Material Compo © Copyright 2005. IPo oustraies international and Pan-	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lowel level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.							
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials an				on		
upplier In	nformation											
Company name* Company unique ID			unique ID		Unique ID Authority			Response Date*				
nsemi									2024-04-20			
Contact Name Title - Contact					Phone - 0	Phone - Contact*			Email - Contact*			
roduct-Env-	-Stewards	viro Compliance		NA				Product-Env-Stewards@onsemi.com				
Authorized Representative* Title - Represent			resentative		Phone - Representative* Email - Representative*							
Product-Env-Stewards Product Enviro Compliance				NA Prod				Product-Env-Stewa	roduct-Env-Stewards@onsemi.com			
Re	Requester Item Number Mfr Iten		Number Mfr Item Name		Effectiv	e Date	Version	Manufacturing Site	Weight*	UOM	Unit Type	
		AR1820HSSC00SH A0-DP1	E 18 MP 1/2.3 CIS		2024-04	-20		TA1	255.05	mg	Each	
[anufactu	ring Proccess Informati	ion										
Ter	Terminal Plating / Grid Array Material Te		e Alloy	J-STD-020 MSL Rati	ng Pea	Peak Process Body Temperature Max Time at P		re Max Time at Peak	Temperature Numb	er of Reflow Cy	cles	
SnAgCu		CU Alloy	CU Alloy 4		260	260 C		30	seconds 3			
				•		-	-					

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	42.75	mg		Misc.	proprietary data		0.1625	mg
			Supplier	Silicon (Si)	7440-21-3		42.1643	mg
			Supplier	Aluminum (Al)	7429-90-5		0.4232	mg
Die Attach	1.88	mg	Supplier	Bisphenol A_Epichlorohydrin Polymer	25068-38-6		0.705	mg
			Supplier	Ethylene Glycol	107-21-1		0.0188	mg
			Supplier	Sulfonium (Thiodi-4,1-phenylene)	89452-37-9		0.0564	mg
			Supplier	Modified Silicon Dioxide (SiO2)	67762-90-7		0.3948	mg
			Supplier	Formaldehyde Polymer	9003-36-5		0.705	mg
Imaging Lens	45.38	mg	Supplier	Titanium Dioxide (TiO2)	13463-67-7		2.269	mg
		C C	Supplier	Sodium Monoxide (Na2O)	1313-59-3		2.269	mg
			Supplier	Boron Trioxide (B2O3)	1303-86-2		2.269	mg
			Supplier	Zinc Monoxide (ZnO)	1314-13-2		2.269	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4		0.2269	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		2.269	mg
			Supplier	Potassium Monoxide (K2O)	12136-45-7		2.269	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		31.5391	mg
Lid Attach	1.95	mg	Supplier	Bisphenol A_Epichlorohydrin Polymer	25068-38-6		0.6162	mg
			Supplier	Filler (SiO2)	68909-20-6		0.1014	mg
			Supplier	Epoxy Prepolymer	Proprietary Data		0.6162	mg
			Supplier	Formaldehyde Polymer	9003-36-5		0.6162	mg
Mold Compound-Black	40.5			Phenolic Resin	proprietary data		6.075	mg
			Supplier	Oxirane	39817-09-9		6.075	mg
			Supplier	1,4-Bis(2,3-epoxypropoxy)butane	2425-79-8		1.215	mg
			Supplier	Carbon Black (C)	1333-86-4		0.405	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		25.92	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		0.81	mg
Solder Ball	35.02		Supplier	Silver (Ag)	7440-22-4		1.0506	mg
			Supplier	Tin (Sn)	7440-31-5		33.7943	mg
			Supplier	Copper (Cu)	7440-50-8		0.1751	mg
Substrate and Solder Mask	87.4	mg	Supplier	Acetophenone	98-86-2		1.713	mg
			Supplier	Fiber Glass (SiO2)	65997-17-3		19.3941	mg

			Supplier	Inorganic Filler of Solder Mask_Talc (Mg3Si4O10(OH)2)	14807-96-6	1.1449	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9	1.1537	mg
			Supplier	Carbon Black (C)	1333-86-4	0.2884	mg
			Supplier	2,4-Diethyl-9H-thioxanthen-9-one (DETX)	82799-44-8	0.2884	mg
			Supplier	Solvent Naphtha (Solvent oil)	64742-94-5	3.4261	mg
			Supplier	Bismaleimide Triazine resin	Proprietary Data	8.74	mg
			Supplier	Copper (Cu)	7440-50-8	42.389	mg
			Supplier	Barium Sulfate (BaSO4)	7727-43-7	8.8624	mg
Wire Bond - Au	0.17	mg	Supplier	Gold (Au)	7440-57-5	0.17	mg